

ABSTRACT OF THE DISCLOSURE

DOUBLE-DISK POLISHING MACHINE, PARTICULARLY FOR TOOLING SEMICONDUCTOR WAFERS

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A double-disk polishing machine, particularly for tooling semiconductor wafers, comprising a machine housing, an upper and a lower working disk, carrier disks for the lower and upper working disks either of which is connected to a vertical driving shaft which, in turn, are rotatably supported in the machine housing by means of roller bearings and are adapted to be driven by a motor via a gear mechanism wherein cooling channels to which a coolant is fed are formed in each carrier disk, characterized in that each of the carrier disks is mounted with the aid of fastening means on a circumferential ring of a wheel-shaped basic carrier which, in turn, is connected to the driving shaft, the radius on which said fastening means lie which connect said basic carrier to said carrier disk is approximately on half the width of the ring-shaped working disk and said basic carrier for the upper working disk is connected to the shaft or to carrier disk in such a way that the inclination of the upper working disk automatically adapts itself to that of the lower working disk when the two working disks bear under a pressure against the interposed workpieces.

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